



#### **FEATURES**

- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- Member of the Texas Instruments Widebus™ Family
- Operates From 1.65 V to 3.6 V
- Max t<sub>nd</sub> of 3 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### (TOP VIEW) 48**∏** 1<del>0F</del> 1DIR L 47 🛮 1A1 1B1 🛮 2 1B2 🛮 3 46 1 1A2 GND 4 45 GND 44 🛮 1A3 1B3 🛮 5 43[] 1A4 1B4 6 42 🛮 V<sub>CC</sub> $V_{CC}$ 41 🛮 1A5 1B5 📙 40**∐** 1A6 1B6 L 39 GND **GND** 10 1B7 11 38 1A7 37 1A8 1B8 🛮 12 13 36 2A1 2B1 🛚 35 2A2 2B2 [] GND 🛮 15 34 GND 16 33 2A3 2B3 32 2A4 2B4 🛮 17 31 V<sub>CC</sub> V<sub>CC</sub> L 18 2B5 🛮 19 30 2A5 2B6 🛮 20 29 2A6 GND [] 21 28 GND 27 2A7 2B7 🛛 22 2B8 🛮 23 26 2A8 24 25 20E 2DIR []

**DL PACKAGE** 

#### DESCRIPTION/ORDERING INFORMATION

This 16-bit (dual-octal) noninverting bus transceiver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74ALVCH16245-EP is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKA	GE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP - DL	Tape and reel	CALVCH16245IDLREP	ALVCH16245
-55°C to 125°C	SSOP - DL	Tape and reel	CALVCH16245MDLREP	ALCH16245M

 Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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## **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

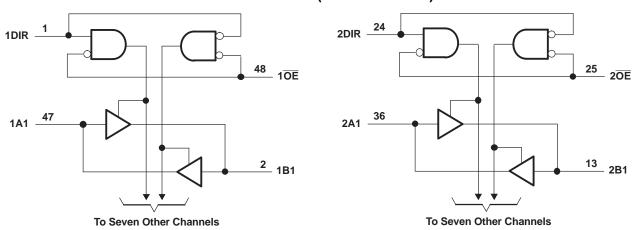
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

# FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	ODEDATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

#### **LOGIC DIAGRAM (POSITIVE LOGIC)**



## **Absolute Maximum Ratings**(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	4.6	V
V	Input valtage renge	Except I/O ports <sup>(2)</sup>	-0.5	4.6	V
VI	Input voltage range	I/O ports <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		<b>-</b> 50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or	GND		±100	mA
$\theta_{JA}$	Package thermal impedance (4)			63	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> This value is limited to 4.6 V maximum.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.





## **Recommended Operating Conditions**(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	
VI	Input voltage		0	V <sub>CC</sub>	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4	
	Lligh lovel output ourrent	V <sub>CC</sub> = 2.3 V		-12	mA
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12	IIIA
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 1.65 V		4	
	Low lovel output ourrent	V <sub>CC</sub> = 2.3 V		12	<b>∞</b> Λ
l <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA
		V <sub>CC</sub> = 3 V		24	
Δt/Δν	Input transition rise or fall rate			10	ns/V
T <sub>A</sub>	Operating free-air temperature (I temp)		-40	85	ô
T <sub>A</sub>	Operating free-air temperature (M temp)		-55	125	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup> MAX	UNIT
	$I_{OH} = -100  \mu A$	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		
	$I_{OH} = -6 \text{ mA}$	2.3 V	2		
V <sub>OH</sub>		2.3 V	1.7		V
	$I_{OH} = -12 \text{ mA}$	2.7 V	2.2		
		3 V	2.4		
	$I_{OH} = -24 \text{ mA}$	3 V	2		
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V		0.2	
	I <sub>OL</sub> = 4 mA	1.65 V		0.45	
	I <sub>OL</sub> = 6 mA	2.3 V		0.4	
V <sub>OL</sub>	101	2.3 V		0.7	V
	I <sub>OL</sub> = 12 mA	2.7 V		0.4	
	I <sub>OL</sub> = 24 mA	3 V		0.55	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V		±5	μΑ
	V <sub>I</sub> = 0.58 V	1.65 V	25		
	V <sub>I</sub> = 1.07 V	1.65 V	-25		
	V <sub>I</sub> = 0.7 V	2.3 V	45		
I <sub>I(hold)</sub>	V <sub>I</sub> = 1.7 V	2.3 V	-45		μΑ
	V <sub>I</sub> = 0.8 V	3 V	75		
	V <sub>I</sub> = 2 V	3 V	-75		
	$V_1 = 0 \text{ to } 3.6 \text{ V}^{(2)}$	3.6 V		±500	
I <sub>OZ</sub> (3)	$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ
I <sub>cc</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ
$\Delta I_{CC}$	One input at $V_{CC} - 0.6 \text{ V}$ , Other inputs at $V_{CC}$ or GND	3 V to 3.6 V		750	μА
C <sub>i</sub> Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		4	pF
C <sub>io</sub> A or B port	$V_O = V_{CC}$ or GND	3.3 V		8	pF

#### **Switching Characteristics**

over recommended operating free-air I temperature (-40°C to 85°C) range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> = 2 ± 0.2	2.5 V : V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	B or A	1	3.7		3.6	1	3	ns
t <sub>en</sub>	ŌĒ	A or B	1	5.7		5.4	1	4.4	ns
t <sub>dis</sub>	ŌĒ	A or B	1	5.2		4.6	1	4.1	ns

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . (2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

<sup>(3)</sup> For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

SCES608A-SEPTEMBER 2004-REVISED JUNE 2006



# SN74ALVCH16245-EP **16-BIT BUS TRANSCEIVER**

### **Switching Characteristics**

over recommended operating free-air M temperature (-55°C to 125°C) range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2. ± 0.2	5 V V	V <sub>CC</sub> = 3 ± 0.3	3.3 V V	UNIT
	(INFOI)	(001701)	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	B or A	1	4.5	1	4.0	ns
t <sub>en</sub>	ŌĒ	A or B	1	8.2	1	5.5	ns
t <sub>dis</sub>	ŌĒ	A or B	1	7.5	1	5.0	ns

## **Operating Characteristics**

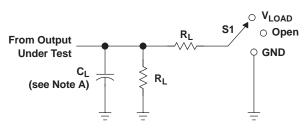
 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
_	Dower dissipation conscitance	Outputs enabled	$C_1 = 50 \text{ pF}.$ $f = 10 \text{ MHz}$	(1)	22	29	pF
$C_{pd}$	Power dissipation capacitance	Outputs disabled	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	(1)	4	5	рг

<sup>(1)</sup> This information was not available at the time of publication.



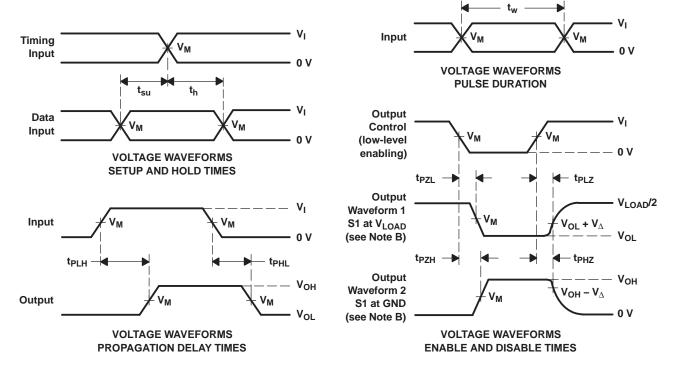
#### PARAMETER MEASUREMENT INFORMATION



TEST	<b>S</b> 1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

V	V		INPUT		V	•	Б	W
V <sub>CC</sub>		VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	$R_L$	$oldsymbol{V}_{\Delta}$
1.8 V		V <sub>CC</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V ± 0.2	V	V <sub>CC</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>500</b> Ω	0.15 V
2.7 V		2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
3 V ± 0.3	v	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 11-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	(1)	(2)			(0)	(4)	(5)		(0)
CALVCH16245IDLREP	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16245
CALVCH16245MDLREP	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ALCH16245M
V62/04763-01XE	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16245
V62/04763-02XE	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ALCH16245M

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN74ALVCH16245-EP:

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## **PACKAGE OPTION ADDENDUM**

www.ti.com 11-Nov-2025

• Catalog : SN74ALVCH16245

NOTE: Qualified Version Definitions:

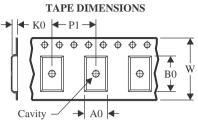
• Catalog - TI's standard catalog product

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CALVCH16245IDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
CALVCH16245MDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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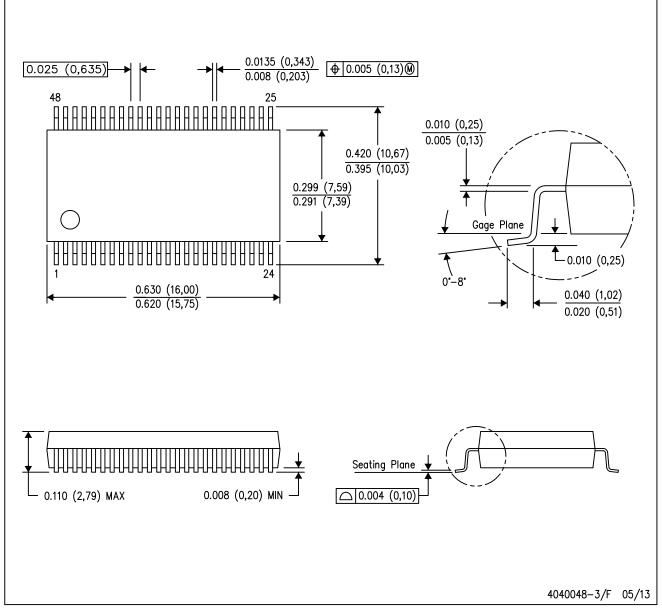


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CALVCH16245IDLREP	SSOP	DL	48	1000	356.0	356.0	53.0
CALVCH16245MDLREP	SSOP	DL	48	1000	356.0	356.0	53.0

## DL (R-PDSO-G48)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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Last updated 10/2025